

### **Features**

- High Dense Cell Design For Extremely Low R<sub>DS(ON)</sub>
- · AEC-Q101 Qualified
- · Rugged and reliable
- · High Speed Switching
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## **Maximum Ratings**

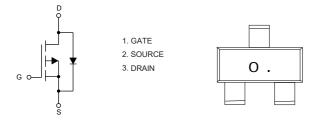
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Maximum Thermal Resistance: 125°C/W Junction to Ambient<sup>(Note 2)</sup>

Parameter	Symbol	Rating	Unit		
Drain -source Voltage		V <sub>DS</sub>	-20V	V	
Gate -Source Voltage		$V_{GS}$	±10	V	
Drain Current-Continuous	T <sub>A</sub> =25°C	. I <sub>D</sub>	-3.4	А	
Drain Current-Continuous	T <sub>A</sub> =70°C		-2.7		
Drain Current-Pulse(Note 2)		I <sub>DM</sub>	-14	Α	
Power Dissipation		P <sub>D</sub>	1.0	W	

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

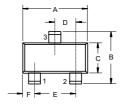
2.Surface Mounted on FR4 Board t<5sec.

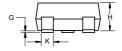
## **Internal Structure and Marking Code**



# **P-Channel MOSFET**

# SOT-23

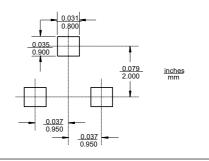






DIMENSIONS						
DIM	INCHES		MM		NOTE	
DIIVI	MIN	MAX	MIN	MAX	NOTE	
Α	0.110	0.120	2.80	3.04		
В	0.083	0.104	2.10	2.64		
С	0.047	0.055	1.20	1.40		
D	0.034	0.041	0.85	1.05		
E	0.067	0.083	1.70	2.10		
F	0.018	0.024	0.45	0.60		
G	0.0004	0.004	0.01	0.10		
Н	0.035	0.041	0.90	1.025		
J	0.003	0.007	0.08	0.18		
K	0.012	0.020	0.30	0.51		
L	0.007	0.020	0.20	0.50		

### **Suggested Solder Pad Layout**





## **ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)**

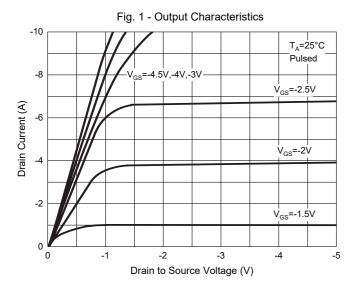
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit	
Static Characteristics					•		
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20			V	
Gate-Threshold Voltage <sup>(Note 3)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.62	-1.0	V	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	μA	
Drain-Source On-Resistance <sup>(Note 4)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.4A		42	51	51 67 mΩ 91	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.0A		55	67		
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-2.5A		76	91		
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-0.75A			-1.2	V	
Dynamic Characteristics <sup>(Note 4)</sup>							
Input Capacitance	C <sub>iss</sub>			438			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V, f=1MHz		76		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			62			
Switching Characteristics <sup>(Note</sup>	4)		,	•	•		
Turn-On Delay Time	t <sub>d(on)</sub>			6.4			
Turn-On Rise Time	t <sub>r</sub>	V <sub>DD</sub> =-10V,V <sub>GS</sub> =-4.5V,		21.8			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D$ =-1A, $R_{GEN}$ =3 $\Omega$		37.4		ns	
Turn-Off Fall Time	t <sub>f</sub>			34			
Reverse Recovery Time	t <sub>rr</sub>			24.5			
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =-3.4A,di <sub>F</sub> /dt=100A/μs		4			
Total Gate Charge	$Q_g$			5.41		<b>50</b>	
Gate-Source Chage	$Q_{gs}$	V <sub>DS</sub> =-10V,V <sub>GS</sub> =-10V,I <sub>D</sub> =-3.4A		1.17		nC	
Gage-Drain Charge	$Q_{gd}$			1.24			

Note: 3.Pulse Test: Pulse Width≤300µs,Duty Cycle≤2%.

4. Guaranteed by Design, Not Subject to Production Testing.



### **Curve Characteristics**



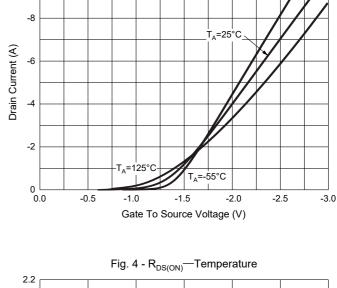
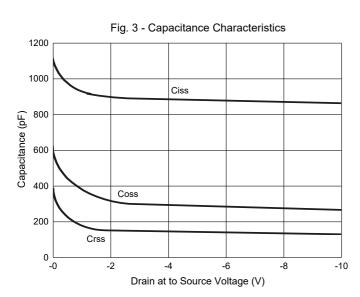
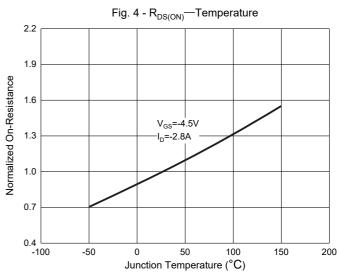
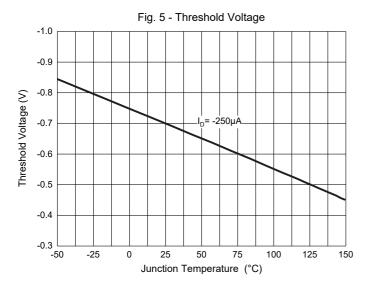


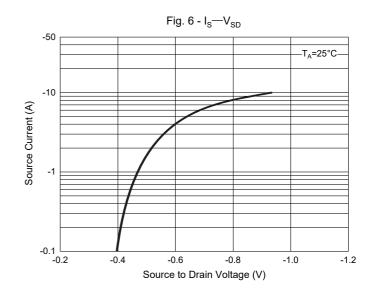
Fig. 2 - Transfer Characteristics

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## **Ordering Information**

Device	Packing
SI2301AHE3-TP	Tape&Reel:3Kpcs/Reel

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